APPARATUS FOR CONTROLLING THERMAL INTERFACE GAP DISTANCE

ABSTRACT

Tolerances in chip (16), substrate and hardware dimensions are accommodated by means of a floating sealing structure to insure that compliant thermally conductive paste (17) disposed between the chip (16) and its lid (20) as trim as possible in order to reduce thermal resistance of the paste (17) so as to be able to run the chip(16) at a cooler temperature. Standoffs (21) are also preferably employed to insure proper paste gap thickness (18).

FIG 1



G00002



162162